

CLAIMS:

1. A method comprising:
grounding a molding tool so as to reduce charge dissipation through an air
5 interface between a stamper and a mirror block of the molding tool.
2. The method of claim 1, further comprising creating a molded component using
the molding tool.
- 10 3. The method of claim 1, further comprising grounding a moving side of the
molding tool.
4. The method of claim 1, further comprising grounding the stamper.
- 15 5. The method of claim 1, wherein grounding the molding tool includes creating an
electrically conductive path between the molding tool and a ground potential.
6. The method of claim 5, wherein the electrically conductive path includes a ground
strap coupled from a moving side of the molding tool to the ground potential.
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7. A molding tool comprising:
a moving side;
a non-moving side; and
a substantially non-resistive path to ground coupled to the moving side.
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8. The molding tool of claim 7, wherein the substantially non-resistive path to
ground comprises a ground strap.
9. The molding tool of claim 7, further comprising substantially non-resistive paths
30 coupled to both the moving side and non-moving sides.

10. The molding tool of claim 7, wherein the non-moving side includes a mirror block and a stamper separated by a small air gap.

5 11. The molding tool of claim 10, wherein the stamper is a nickel stamper and the mirror block includes a diamond-like carbon coating.

12. The molding tool of claim 10, wherein the stamper is a nickel stamper and the mirror block includes a titanium nitride coating.

10 13. The molding tool of claim 10, wherein the stamper is vacuum drawn to the mirror block.

14. The molding tool of claim 7, wherein the non-moving side includes a mirror block and does not include a stamper.

15 15. The molding tool of claim 7, wherein both the moving side and non-moving side include a mirror block and a stamper.

20 16. The molding tool of claim 7, wherein the molding tool is an injection molding tool.

17. A molding tool comprising:
a first side and a second side collectively defining a mold cavity; and
a ground strap defining at least a portion of a substantially non-resistive path from
25 the mold cavity to ground.

18. The molding tool of claim 17, wherein the molding tool includes a stamper and a mirror block on the first side, wherein the stamper and mirror block are separated by a small air gap, and wherein the ground strap substantially reduces charge dissipation
30 across the small air gap.

19. The molding tool of claim 18, wherein the ground strap is coupled to the second side.

20. The molding tool of claim 19, wherein the second side is a moving side and the
5 first side is a non-moving side.

21. The molding tool of claim 17, wherein the molding tool is an injection molding tool.

10 22. A molding system comprising:

a molding tool including a moving side, a non-moving side, and a substantially non-resistive path to ground coupled to the moving side;

a control unit coupled to the molding tool to control a molding process of the molding tool; and

15 a robotic arm coupled to the control unit for receiving molded components from the molding tool.